

ABSTRACT OF THE DISCLOSURE

An embodiment of an integrated circuit die with staggered bond pads and optimized driver layout includes a staggered array of bond pads with an outer ring of bond pads and an inner ring of bond pads. Driver/ESD circuit cells for the outer ring of bond pads are located to the outside of the bond pads (between the outer ring of bond pads and the nearest die edge). The driver/ESD cells for the inner ring of bond pads are located to the inside of the bond pads (between the inner ring of bond pads and the die core). The integrated circuit die is coupled to a lead frame via bond wires.